



Clearwater Forest the Next Generation Intel® Xeon® Processor with Efficiency Cores

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Performance varies by use, configuration and other factors. Learn more on the Performance Index site.

Performance results are based on testing as of dates shown in configurations and may not reflect all publicly available updates. See backup for configuration details. No product or component can be absolutely secure.

Results have been estimated or simulated.

Your costs and results may vary.

Intel technologies may require enabled hardware, software or service activation.

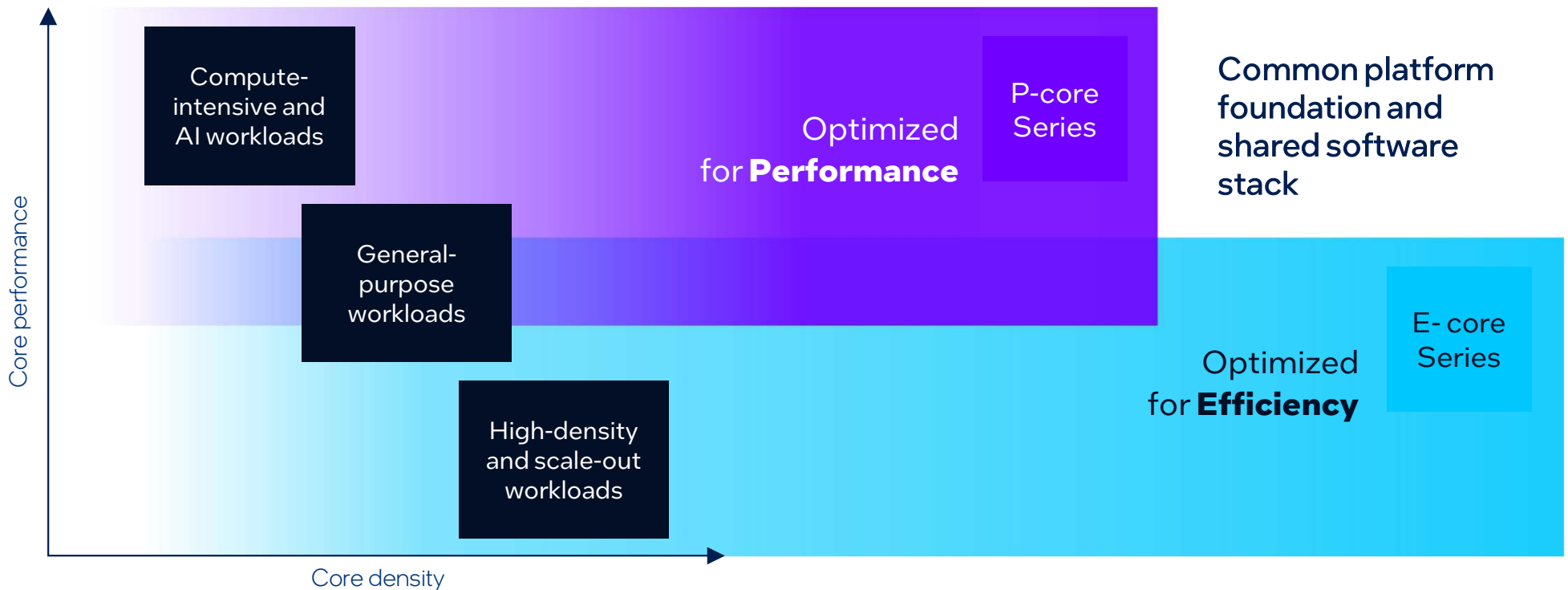
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Intel® Xeon® 6, Designed to Address Market Needs

The best processors to meet diverse performance and efficiency requirements



For more Intel Xeon 6 product detail visit <https://www.intel.com/content/www/us/en/content-details/834093/content-details.html>



Intel Clearwater Forest

Performance and Power Efficiency

Addressing modern computing needs across data center and networking with a focus on TCO and performance per Watt for high-density compute and scale-out workloads

Intel's latest process node, 18A

Improved performance and power efficiency

Intel's latest Efficiency Core Architecture

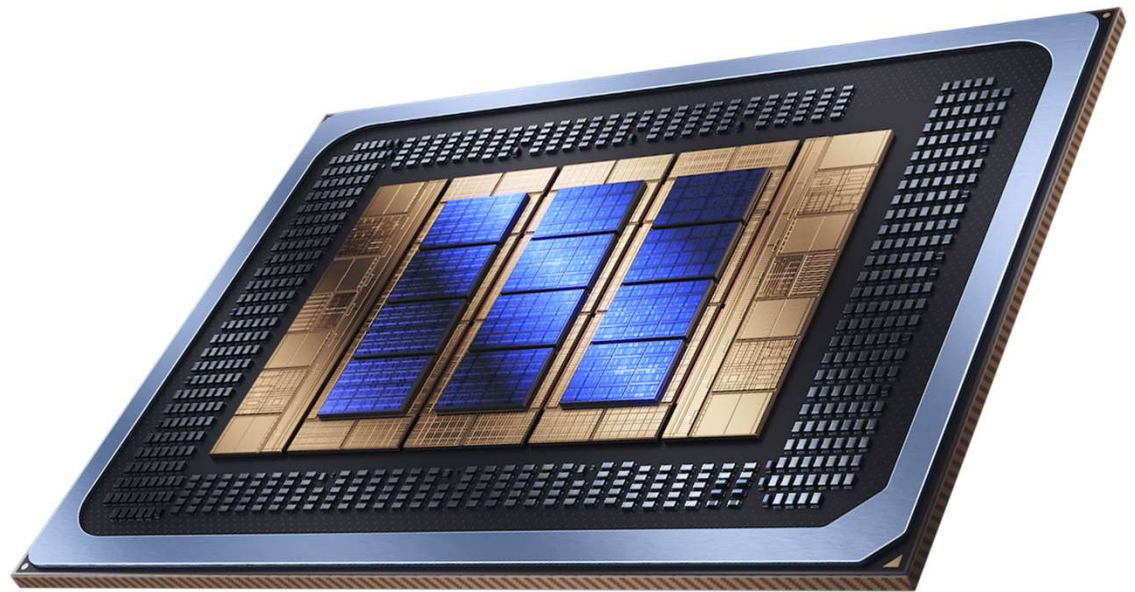
IPC uplift tuned for 18A process

Intel Foveros Direct 3D Construction

Shorter, power efficient routes, larger last level cache (LLC)

Increased Memory Bandwidth

12 channel DDR5 8000



For more information visit <https://www.intel.com/content/www/us/en/foundry/process/18a.html>

Intel 18A Process

Backside metal combined with gate-all-around provide numerous benefits beyond FET Z scaling

Intel's latest process node, 18A

Lowered gate capacitance improves core logic power efficiency

Higher Cell Density

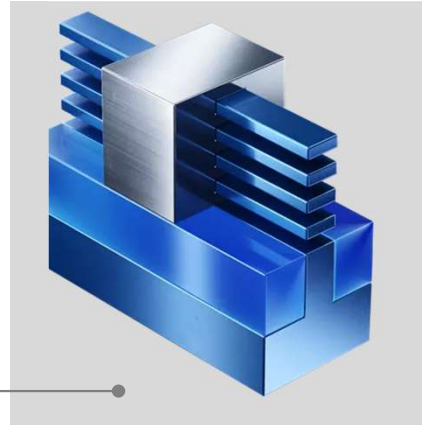
Over 90% cell utilization¹

Improved Signal Routing

Reduces RC delay, improves power efficiency

Low Loss Power Delivery

Reduce losses by 4-5%²



¹ <https://newsroom.intel.com/client-computing/powervia-test-shows-industry-leading-performance>

² 2023 VLSI Symposium "E-Core Implementation in Intel 4 with PowerVia (Backside Power) Technology", Manju Shamanna

Clearwater Forest E-core

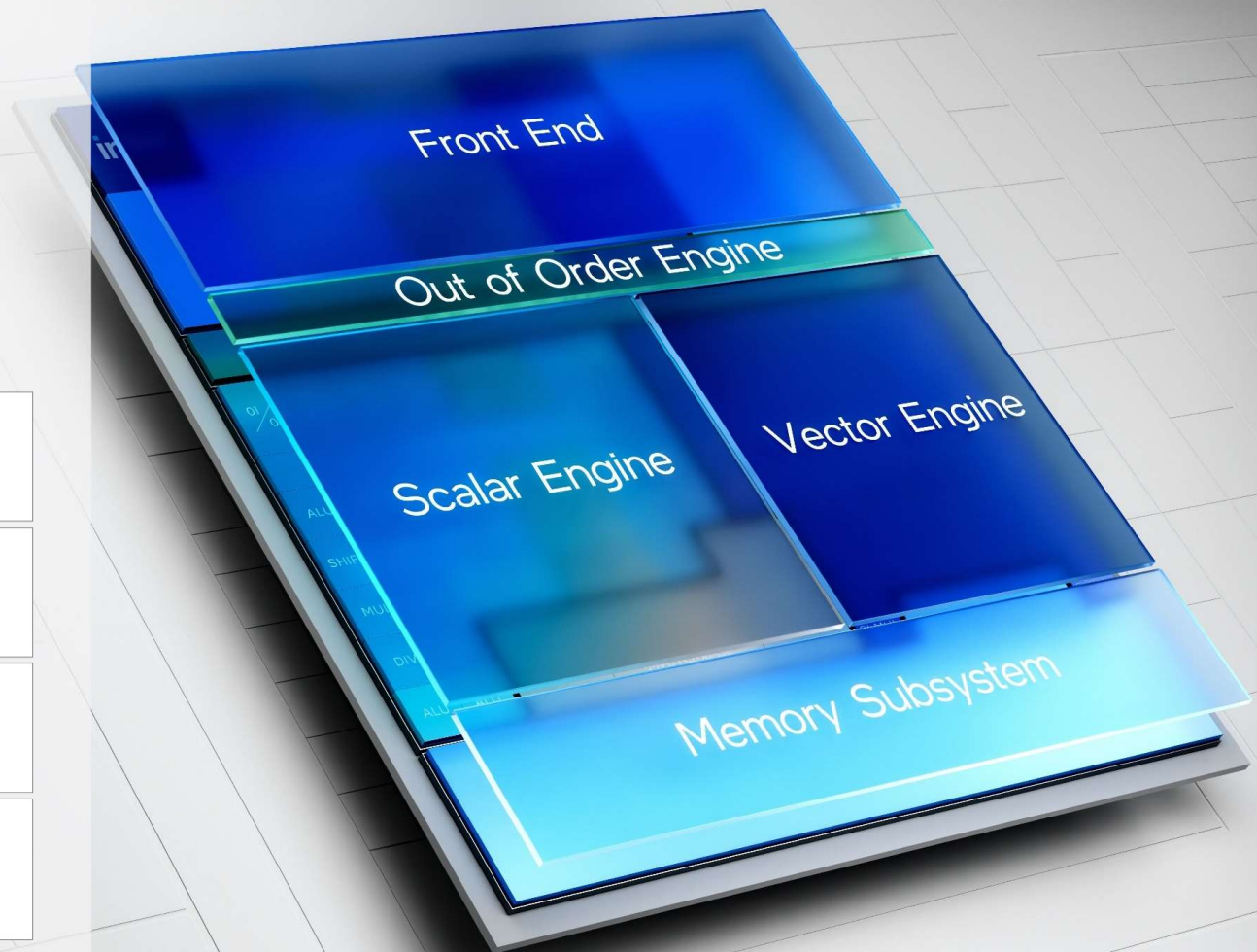
Architectural Leaps forward
for E-core based Xeons

Smarter Front-End

Deeper out of Order Engine

Bigger Scalar and Vector Execution

Enhanced memory Subsystem



Clearwater Forest E-core

Front-End

64kB Instruction Cache

with on-demand instruction length decoder
accelerating workloads with large code footprints

Nine instructions decoded per cycle

Three 3-wide instruction decoders provide **50% more instruction bandwidth** while keeping power and latency in check

More accurate branch prediction

through deep branch history
and larger structure sizes



Clearwater Forest E-core

Out-of-Order Engine

**Eight-wide allocation (1.6x)
with sixteen-wide retire (2x)**

Provides execution parallelism

416 entry out of order window (1.6x)

Discovers data parallelism

Twenty-six execution ports (1.5x)

Executes data parallelism

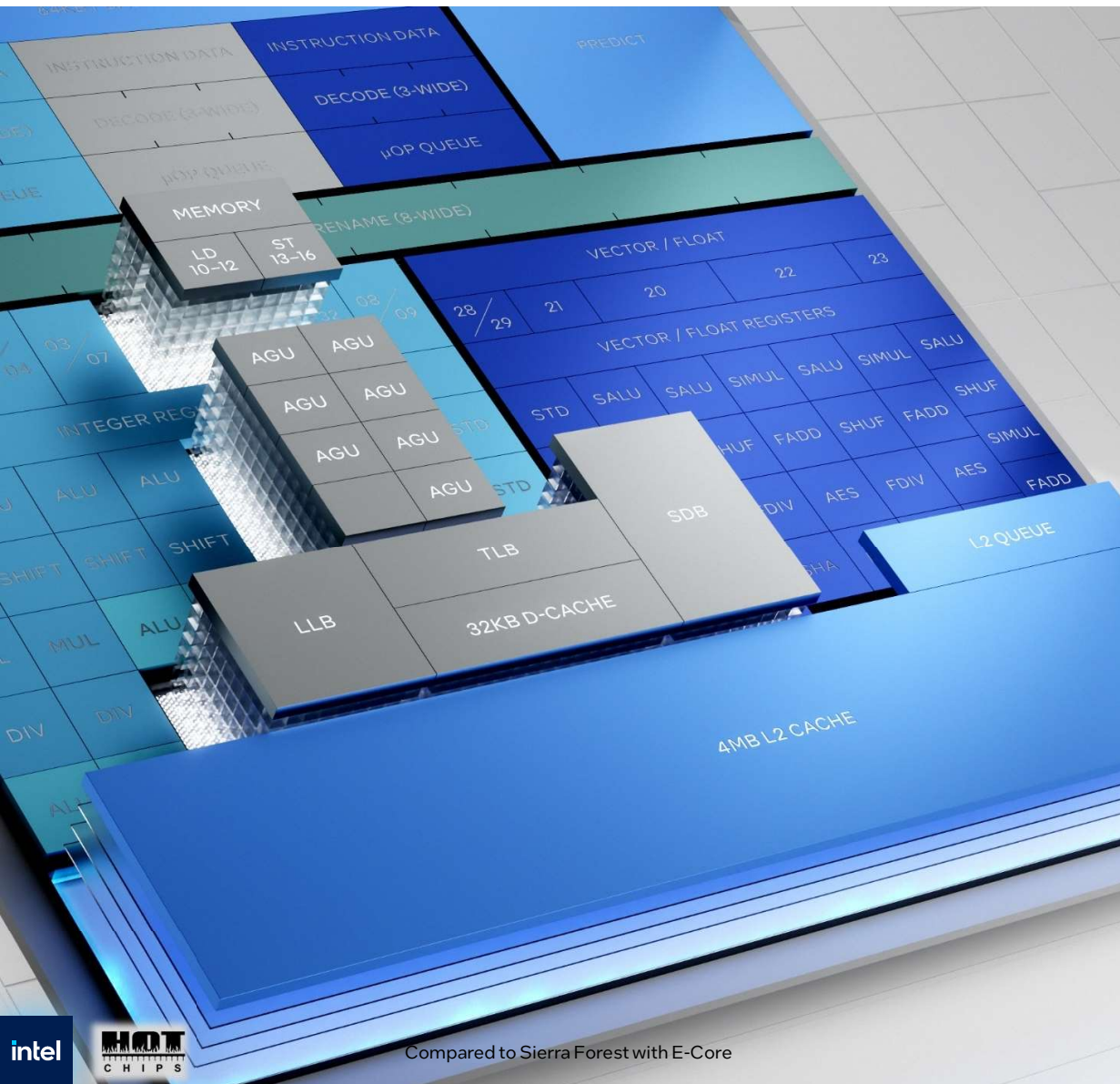


Execution Engine

Addresses a breadth of workloads
Dedicated hardware improves efficiency

Integer Execution (2x)
Vector Execution (2x)
Load Address Generation (1.5x)
Store Address Generation (2x)





Clearwater Forest E-core

Core Memory Subsystem

Three Load (1.5x) + Two Store (1.0x)

Issuing loads earlier may reduce latency

Deep buffering

Supporting 128 outstanding L2 misses (2x)

Advanced Prefetchers

At all cache levels to detect a wide variety of streams

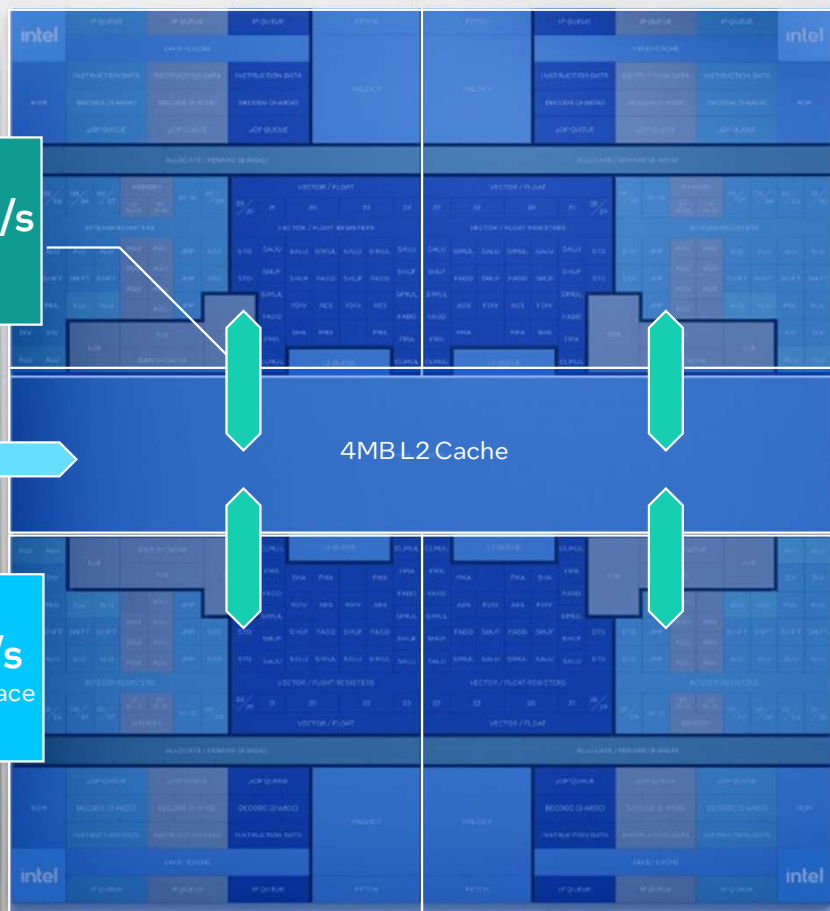
Xeon® Advanced Features

- L1 Data Cache ECC
- Data Poisoning Support
- Recoverable Machine Check
- Local Machine Check
- 52 physical address bits
- Core Lockstep

Compared to Sierra Forest with E-Core

200 GB/s
per core

35 GB/s
fabric interface



Clearwater Forest E-core

Module Architecture

4MB Unified L2

Shared among four cores with 17 cycles of latency

4 Cores per module

Area efficient construction

Twice the L2 Cache Bandwidth

400 GB/s

17% Instructions per cycle increase

SpecIntRate'17 estimated projection

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3D Construction

Optimize for each process node

Twelve CPU Chiplets on Intel 18A

E-core modules

Three Base Chiplets on Intel 3

Fabric, LLC, memory controllers and IO

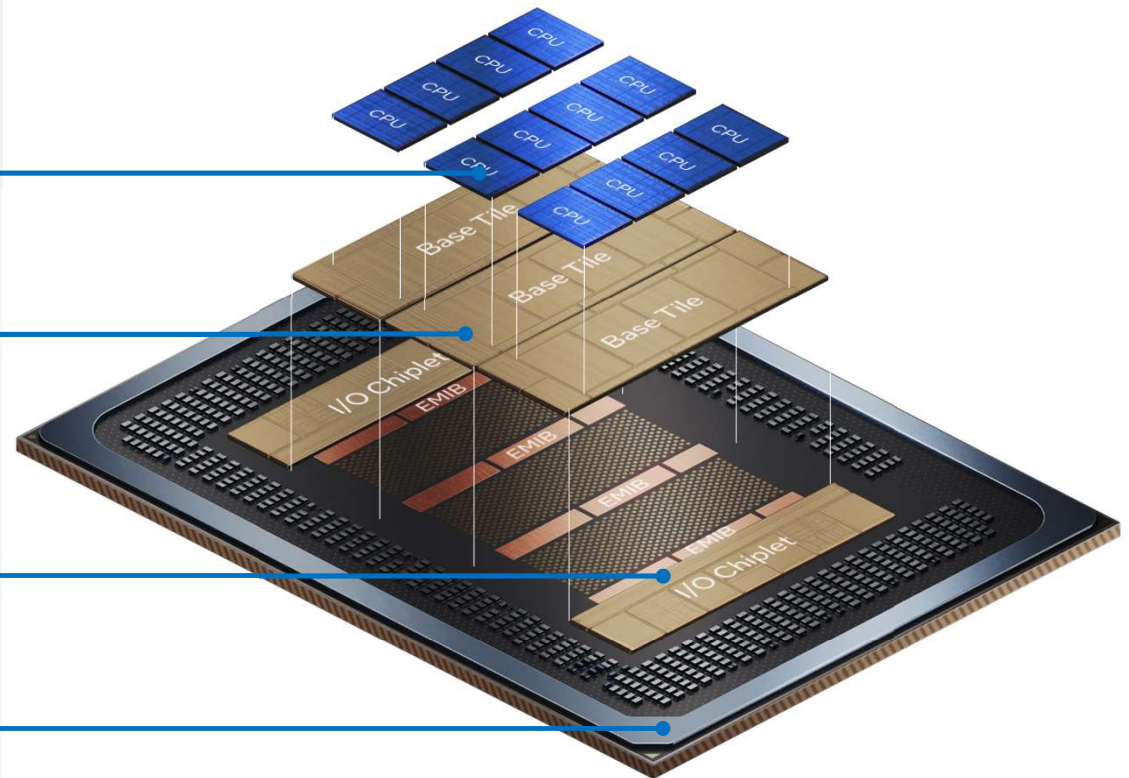
Two I/O Chiplets on Intel 7

High speed I/O, fabric and accelerators

Xeon 69xxE/P Platform Compatible

Monolithic mesh coherent fabric

Power efficiency from shorter routes, more metal resources, high density interconnect



Clearwater Forest

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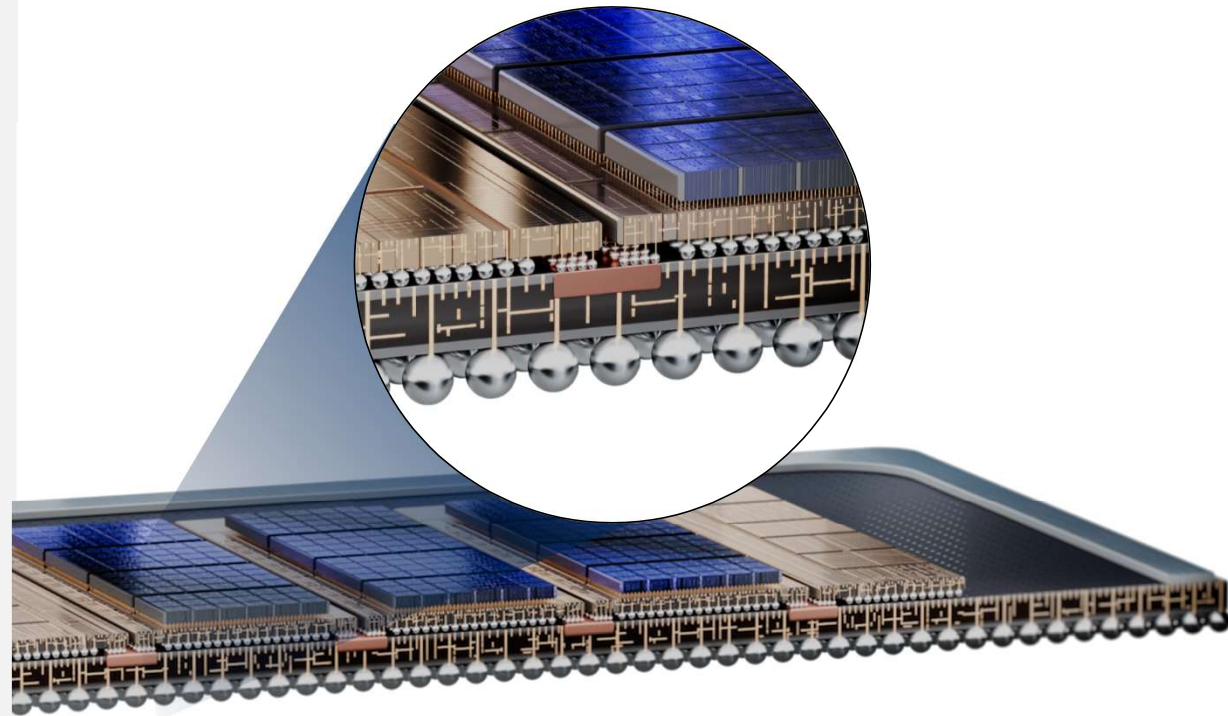
Two I/O Chiptlets on Intel 7

High speed I/O, fabric and accelerators

Xeon 69xxE/P Platform Compatible

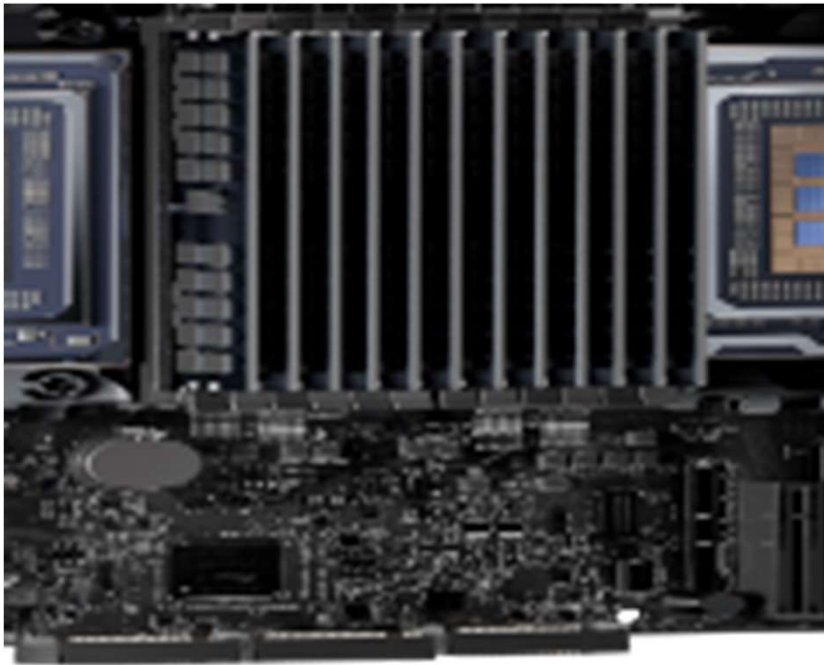
Monolithic mesh coherent fabric

Power efficiency from shorter routes, more metal resources, high density interconnect



Clearwater Forest

Performance



2x 12 channels DDR5 8000

Memory bandwidth to support performance increase

1300 GB/s*
3 TB

2x 96 Lanes Gen 5 PCIe, 64 CXL

IO bandwidth and connectivity

1000 GB/s
96 devices

144 Lanes UPI Coherency

High bandwidth, low latency remote memory access

576 GB/s

576 cores, 1152 MB LLC

59 TF/s
5000 GB/s

*2 socket 100% read bandwidth 2R x4
Results are based on architectural projections as of August 2025

The logo features the word "intel" in a lowercase sans-serif font, followed by a large "x" symbol. To the right of the "x" is the "HOT CHIPS" logo, which consists of the word "HOT" in a bold, blocky font with a flame-like pattern underneath, and the word "CHIPS" in a smaller, spaced-out sans-serif font below it.

intel x **HOT**
CHIPS

***Thank
You***